

JOB DESCRIPTION - EXEMPT

Position Title:	Wirebond Engineer			Position # or Level :	
Department:	Engineering		Reports to:	TBD	
Employment Status:	(Indicate if position is full time or part time)	Pay Grade or salary range:	(List the pay grade or salary range for this position)	% Travel Required	(List % of travel for this position)

Position Summary: The Wire Bond Engineer is responsible for developing, optimizing, and maintaining wire bonding processes used in semiconductor packaging and microelectronics manufacturing. This role focuses on improving product quality, process capability, yield, reliability, and manufacturing efficiency while supporting new product introductions and production operations.

Essential Duties:
Other Duties & Responsibilities (Optional)

- Develop, qualify, and optimize wire bonding processes for semiconductor packages
- Perform process characterization, DOE (Design of Experiments), and root cause analysis to improve yield and reliability.
- Define process parameters, work instructions, specifications, and control plans.
- Support new product introduction (NPI) in a high mix manufacturing line.
- Deploy / use industry best practices for process set up, control and changeovers
- Analyze SPC data and identify opportunities for continuous process improvement.
- Collaborate with Quality, Production and Engineering teams to resolve issues.
- Lead corrective and preventive actions (CAPA) for process-related issues.
- Ensure compliance with customer, industry, and internal quality standards.
- Train technicians and operators on wire bonding processes and best practices.

Minimum Qualifications:

- Bachelor's degree in electrical engineering, Mechanical Engineering, Materials Science, Semiconductor Engineering, or related field.
- 5+ years of experience in wire bonding, semiconductor packaging, or microelectronics manufacturing.
- Hands-on experience with automatic wire bonders (gold, copper, aluminum wire bonding).
- Knowledge of wire bonding principles, semiconductor assembly and package technologies.
- Experience with statistical tools such as SPC, DOE, and FMEA.
- Strong problem-solving and data analysis skills.
- Excellent communication and teamwork abilities.

Key Competencies:

- Wire Bond Process Development
- Semiconductor Packaging

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- Failure Analysis
- Yield Improvement
- Root Cause Analysis
- SPC & Process Control
- Disciplined with excellent attention to detail and robust process control

- Preferred Skills:**
- Experience with advanced packaging technologies, including BGA, QFN, SIP, and Flip Chip.
 - Familiarity with SEM, failure analysis techniques, and reliability testing.
 - Knowledge of Lean Manufacturing and Six Sigma methodologies.
 - Green Belt or Six Sigma certification preferred.

Work Environment: While performing the duties of the job, the employee is regularly required to sit, stand and/or walk for extended periods of time; use hands and fingers; reach with hands and arms; and talk and hear.
 Ability to lift 30 pounds
 Observe ESD and safety practices
 Wear cleanroom attire on occasion
 Must be a U. S. Citizen or Permanent Resident

Employee Acknowledgement:

I have read this job description, and I fully understand all my job duties and responsibilities.

Print Name	Signature	Date	
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